

C2
the base 202 by a support 204. The arm moves up and down in the direction of the support 204 so that the probe head 40 engages an integrated circuit device on the wafer 50. Figure 18 schematically show an apparatus for moving probe structure 100 towards and away from electronic device 204 so that probe tips 210 engage and disengage electrical contact locations 212 on electrical device 204. Probe 10 is mounted on to holder 200 having means 214 for applying electric power to the probe tips 210. Electronic device 206 is held on base 206. Holder 200 is physically connected to support 202 which is connected to arm 208 which is connected to base 206. Support 202 is adapted for up and down movement.

IN THE CLAIMS

In claims 22 and 23, line 8 before “;” add --ending in probe tip ends-- FAX COPY RECEIVED

REMARKS

FEB 13 2001

TECHNOLOGY CENTER 2800

Reconsideration is respectfully requested in view of any changes to the claims and the remarks herein. Please contact the undersigned to conduct a telephone interview in accordance with MPEP 713.01 to resolve any remaining requirements and/or issues prior to sending another Office Action. Relevant portions of MPEP 713.01 are included on the signature page of this amendment.

Claims 12-13 and 22-23 have been rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicants regards as the invention. Applicants respectfully disagree and request withdrawal of this rejection.

In claim 12, “a means for disposing said probe tip ends in electrical contact with locations on said electronic device” is shown in added Figure 17 and 18 and the text added to the specification corresponding to these added figures support for the added figures and text as through out the specification. In claim 13, the language “a depression surrounding at least one of

S.N. 09/088,394

- 2 -

Docket No.: YO993-028AB

34

C